Material Data Form

Manufacturer Part & Version No.	**BCN31SB**
Date of completion. dd/mm/yyyy	5/24/2005

Manufacturer contact Information	
Contact Name	Ted Whitehill
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Manufacturer name.	Total Mass of the Unit specified in (g):	Unit / Comp. Description. (e.g. CHIPRES 0W125 1R0 J 1206)	Breakdown of component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name. (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass. (g)
BI	0.0391	BCN318SB***J7	Alumina Substrate	Alumina	Aluminum Oxide	1344-28-1	0.030192
					Silicon Dioxide	14808-60-7	0.0009435
					Magnesium Oxide	1309-48-4	0.0001887
					Calcium Oxide	1305-78-8	0.0000942
					Sodium Oxide	1313-5-3	0.00003145
			Thick Film	Conductor	Silver	7440-22-4	0.0008625
					Lead in Glass Frit	65997-18-4	0.00000575
					Other		0.00028175
			Thick Film	Resistor	Lead in Glass Frit	65997-18-4	0.00007
					Silver	7440-22-4	0.00006125
					Other		0.00016875
			Thick Film	Encapsulant	Lead in Glass Frit	65997-18-4	0.00021
					Other		0.00039
			Thick Film	Encapsulant	Lead in Glass Frit	65997-18-4	0.0006625
					Iron Cobalt Chromate	68186-97-0	0.000265
					Other		0.0003975
			Thick Film	Encapsulant	Lead in Glass Frit	65997-18-4	0.000048
					Titanium Dioxide	13463-67-7	0.000006
					Other		0.000066
			Thick Film	Encapsulant	Lead in Glass Frit	1317-36-8	0.0009
					Zinc Oxide	1314-13-2	0.000054
					Other		0.000846
			Thick Film	Conductor	Silver	7440-22-4	0.000552
					Cobaltic Oxide	1308-06-1	0.000092
					Lead in Glass Frit	65997-18-4	0.000046
					Other		0.00023
			Plating		Nickel	7440-02-0	0.0003116
					Tin	7440-31-5	0.001128
				Total			0.03910